

Electronic Acknowledgement Receipt

EFS ID:	9025687
Application Number:	10755042
International Application Number:	
Confirmation Number:	8665
Title of Invention:	Integrated chip package structure using silicon substrate and method of manufacturing the same
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/ShirLynn Mata
Filer Authorized By:	Dennis Alan Duchene
Attorney Docket Number:	085027-0104
Receipt Date:	13-DEC-2010
Filing Date:	09-JAN-2004
Time Stamp:	20:05:22
Application Type:	Utility under 35 USC 111(a)

Payment information:

Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$180
RAM confirmation Number	6878
Deposit Account	502624
Authorized User	

The Director of the USPTO is hereby authorized to charge indicated fees and credit any overpayment as follows:

Charge any Additional Fees required under 37 C.F.R. Section 1.21 (Miscellaneous fees and charges)

File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/Message Digest	Multi Part/.zip	Pages (if appl.)
1	Transmittal Letter	InformationDisclosureStatementTransmittal1-085027-0104.pdf	71355 ee8128a8c8226e2432d52d9a69f7e330488 6a2a7	no	3

Warnings:**Information:**

2	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureStatement1-085027-0104.pdf	88479 585da92d7179a60142e15423b05eb211c1 0028af	no	1
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Warnings:**Information:**

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3	Foreign Reference	TW423132_FRN00113_pdf.pdf	1647015 ff19b3f3932b35759ec4ee9a0bbe051ae88f ec40	no	42
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Warnings:**Information:**

4	Foreign Reference	TW452930_FRN00112_pdf.pdf	2916399 41998b2d4c3c73f7cbbadba958bb92fede 5c97d	no	47
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Warnings:**Information:**

5	Foreign Reference	TW466652_FRN00111_pdf.pdf	959341 8b2062231288e73e51bbef7d4d4c558933e 977bc	no	31
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Warnings:**Information:**

6	Transmittal Letter	InformationDisclosureStatementTransmittal2-085027-0104.pdf	66975 360f7cc94435173347481d72c301e781914 7a55b	no	2
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Warnings:**Information:**

7	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureStatement2-085027-0104.pdf	90717 ea9222549fd9085b1aa8a1353af20b0dbd0 1073d	no	2
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Warnings:**Information:**

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8	Transmittal Letter	InformationDisclosureStatementTransmittal3-085027-0104.pdf	67641 43f67d6b4efe7ccbb770df38167ae681279b dcdb	no	2
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Warnings:

Information:					
9	Information Disclosure Statement (IDS) Filed (SB/08)	InformationDisclosureStatement3-085027-0104.pdf	106796 b8b05cf2eadf4700a386de2395aafc68c10b4caf	no	3
Warnings:					
Information:					
This is not an USPTO supplied IDS fillable form					
10	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 072127b124142b87d48b36305577e00d7f281092	no	4
Warnings:					
Information:					
11	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109 daa31204b1d9d203a708a79ef619df4655068f74	no	9
Warnings:					
Information:					
12	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a340bdb7c9b1547370da4bc4129a0cd8aaeb74	no	7
Warnings:					
Information:					
13	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 789f5c75db4f5367e2064f35e1853c2a9776ebb5	no	6
Warnings:					
Information:					
14	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6ea9c2af4c3f93c0d5e8d84fcc64bb8318ee28a	no	5
Warnings:					
Information:					
15	NPL Documents	6_HU_Copper_Polymide.pdf	436455 60f30badcc448865be25da92121b117fce267a05	no	7
Warnings:					
Information:					
16	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8132037f7462423e7e041a4f39e24a5e4578ab27	no	8
Warnings:					
Information:					

17	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726022251835f4d292326de7bc282d5944 1d614	no	4
Warnings:					
Information:					
18	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 ab71bc6a4d8720a9b8f6ef9476e4dc5e395 eebb5	no	4
Warnings:					
Information:					
19	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 9501660bd4c4309f18b1797ed0026a7b2bc 14322	no	4
Warnings:					
Information:					
20	NPL Documents	11_VENKATESAN_A_High_performance_1_8V.pdf	618169 7bc331a4bbe29891fc13105b6c5bc7609f2c 568d	no	4
Warnings:					
Information:					
21	NPL Documents	12_JENEI_HighQInductors.pdf	279415 1749e7bdbf20e8e3cce6d074bc3723f8ed b831	no	3
Warnings:					
Information:					
22	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BiCMOS_process.pdf	420788 8e26f2f669459e3ce07d15bd587c4a335999 fa0e	no	4
Warnings:					
Information:					
23	NPL Documents	14_SAKRAN_implementation_of_65nm.pdf	1254646 3b466f954664fc7184e7330836837d22ae0 8c5a1	no	3
Warnings:					
Information:					
24	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c0afedaf905c311cf91a55df92d1793f8f43 7f	no	2
Warnings:					
Information:					
25	NPL Documents	16_BOHR_presentation_Intel_ISSCC_09_plenary.pdf	8968148 288c45398d711068a36020473b6c927da65 28428	no	66
Warnings:					
Information:					

26	NPL Documents	17_PDF_BOHR_plenary_paper _Intel_ISSCC_09_pdf.pdf	1615786 eb378566ef634b46f17c05834bcae224a088 acc3	no	6
Warnings:					
Information:					
27	NPL Documents	18_PDF_INGERLY_Low_K_Inter connect_IEEE_2008_pdf.pdf	651359 8e1a8daecb73909145098b76a9b7e881109 72a58	no	3
Warnings:					
Information:					
28	NPL Documents	19_PDF_KURD_Next_generatio n_intel_2008_pdf.pdf	259226 19abd2c18c024cec75924c92bed9ec698a6 5fc4a	no	2
Warnings:					
Information:					
29	NPL Documents	20_PDF_MALONEY_Novel cla mp_circuits_for_IC_power_sup ply_protection_pdf.pdf	191082 d68b46b342e836f0eda7955b62f727a63e 41cd7	no	12
Warnings:					
Information:					
30	NPL Documents	21_PDF_GEFFKEN_Overview_o f_polymide_pdf.pdf	851514 e18b14453fb0b5d803d7a37663977c5306a b7dea	no	11
Warnings:					
Information:					
31	NPL Documents	22_PDF_LUTHER_Planar_Copp er_pdf.pdf	2095781 90afd29bd75e9d46783563e765b92e1c2d6 87a5a	no	8
Warnings:					
Information:					
32	NPL Documents	23_PDF_MASTER_Ceramic_Ball _Grid_Array_pdf.pdf	1069512 bd6eeeaa156a9033c17b7766d18810a6d0f3 58a0b	no	5
Warnings:					
Information:					
33	NPL Documents	24_PDF_MALONEY_Stacked_P MOS_clamps_for_high_voltage _power_supply_protection_pd f_pdf.pdf	1327621 bf7256b30d3890a26269a1501436f32580e bde88	no	8
Warnings:					
Information:					
34	NPL Documents	25_PDF_LIN_A_New_System_ On_Chip_Technology_pdf.pdf	390082 420f653caeaa0b51f8d8465f872b9a351e6fa 4296	no	7
Warnings:					
Information:					

35	NPL Documents	26_PDF_MEGICA_Brochure_leaflets_01_28_04_pdf.pdf.pdf	888383 aec89db5e67eb17d33ea9f52144d8fb181fd9a	no	3
Warnings:					
Information:					
36	NPL Documents	27_PDF_LIN_Post_Passivation_Technology_Presentation_for_TSMC_Tech_Symposium_2003.pdf.pdf	1277639 20556e2754a2807cec285bcc5d87f24d52717e89	no	32
Warnings:					
Information:					
37	NPL Documents	28_PDF_LIN_A_New_IC_Connection_Scheme_and_Design.pdf.pdf	116206 e1e1d6bb5ccf0007c76b6677a40a8a47106eecb8	no	4
Warnings:					
Information:					
38	Fee Worksheet (PTO-875)	fee-info.pdf	29743 1eece6631d611695ed835fc3a64f706b27d65937	no	2
Warnings:					
Information:					
Total Files Size (in bytes):				46820436	
<p>This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.</p> <p>New Applications Under 35 U.S.C. 111 If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.</p> <p>National Stage of an International Application under 35 U.S.C. 371 If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.</p> <p>New International Application Filed with the USPTO as a Receiving Office If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.</p>					